

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A method for producing parts for passive electronic components comprising:
 - producing a laminated strip having at least one stack formed by alternately stacking a thin and fragile metal strip and a layer of an adhesive material, and
 - forming at least one part for the passive electronic components out of the laminated strip by cutting the laminated strip,
 - wherein the cutting of the laminated strip comprises at least one step involving etching by sandblasting,
 - wherein prior to the etching by sandblasting, arranging, on a face of the laminated strip, a cover composed of a material which is resistant to sandblasting, the cover comprising at least one opening having at least one shape.
2. (previously presented): The method according to claim 1, wherein the layer of adhesive material of the at least one stack is a layer of a fragile and hard adhesive material.
3. (previously presented): The method according to claim 1, wherein the thin and fragile metal strip of the at least one stack is constituted by a material selected from the following

alloys: nanocrystalline magnetic alloys, fragile magnetic alloys of iron-cobalt, iron-platinum, iron-silicon, iron-nickel, fragile nickel-chromium alloys, fragile molybdenum alloys and fragile tungsten alloys.

Claim 4 (cancelled).

5. (previously presented): The method according to claim 1, wherein the cover is a steel strip which is resistant to sandblasting.

6. (previously presented): The method according to claim 1, wherein the cover is constituted by a resilient layer.

7. (previously presented): The method according to claim 6, further comprising depositing the resilient layer by serigraphy, wherein the resilient layer is a layer of paint.

8. (previously presented): The method according to claim 6, wherein the resilient layer is a layer of resilient photosensitive resin formed by exposing the resilient photosensitive resin to light radiation through a mask which comprises appropriate cut-outs, and developing the resilient photosensitive resin by immersion in a bath before the etching by sandblasting is performed.

9. (original): Method according to claim 1, characterised in that the laminated strip(10, 100) is constituted by at least two alternate stacks (11, 12, 110, 120) of thin metal strips and layers of a fragile and hard adhesive material, the at least two alternate stacks being superimposed and separated by means of an adhesive layer (33, 330), at least a portion of which is constituted by a resilient material which is resistant to etching by means of sandblasting.

10. (previously presented): The method according to claim 1, wherein, prior to carrying out the etching by sandblasting, bonding the laminated strip to a support strip or plate.

11. (previously presented): The method according to claim 10, wherein, after cutting by sandblasting, separating the cut laminated strip from the support strip.

12. (previously presented): The method according to claim 10, wherein, prior to carrying out the etching by sandblasting, placing the laminated strip and the support strip in a sandblasting etching chamber comprising at least one sandblasting nozzle which projects a jet of abrasive particles, and moving the laminated strip and the at least one sandblasting nozzle in order to pass over the surface of the laminated strip with the jet of abrasive particles.

13. (previously presented): The method according to claim 1, wherein a plurality of parts for electronic components are formed out of the laminated strip by etching, the plurality of parts

being connected to each other by attachment points, and wherein the plurality of parts are separated after etching.

14. (previously presented): The method according to claim 2, wherein the fragile and hard material is an epoxy adhesive.

15. (previously presented): The method according to claim 10, wherein the support strip is a strip comprising a layer of polymer and a layer of conductive material such as copper.

16. (original): Method according to claim 15, characterised in that the support strip (51) further comprises, before cutting by means of sandblasting, at least one electronic component which is protected during the sandblasting cutting operation by means of a layer of resilient material.

Claims 17-23 (cancelled).

24. (previously presented): A method for producing a passive inductive electronic component comprising:

forming a part which is cut from a laminated strip constituted by a stack of thin metal strips of a magnetic alloy,

wherein the part is produced using the method according to claim 1, and

further comprising winding and coating of the component with a protective material.

25. (previously presented): A method for producing a passive electronic component which is capacitive or resistive, comprising:

forming a part which is cut from a laminated strip constituted by a stack of thin metal strips and a portion for electrical connection,

wherein the part is produced using the method according to claim 1, and

further comprising producing the electrical connection portion and coating the component with a protective material.

Claim 26 (cancelled).

27 (new) The method according to claim 1, characterised in that the part is a core of a passive inductive electronic component.

28. (new): The method according to claim 27, characterised in that the part comprises an air gap.

29. (new): The method according to claim 27, characterised in that the part is a torus having a thickness of less than 1 mm.

30. (new): The method according to claim 27, characterised in that the part comprises at least two parts having different thicknesses.

31. (new): The method according to claim 1, characterised in that the part is a fitting for an electrical capacitor.

32. (new): The method according to claim 1, characterised in that the part constitutes an electrical resistor.